



Material Content Data Sheet



Sales Product Name		IPB80P03P4L-07		Issued		29. August 2013			
MA#		MA000461996							
Package		PG-TO263-3-2		Weight*		1.46 g			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [g]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.002	0.15	0.15	1516	1516	
leadframe	non noble metal	iron	7439-89-6	0.001	0.06		583		
	inorganic material	phosphorus	7723-14-0	0.000	0.02		175		
	non noble metal	copper	7440-50-8	0.852	58.21	58.29	582129	582885	
wire	non noble metal	aluminium	7429-90-5	0.004	0.27	0.27	2689	2689	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.00		0		
	organic material	carbon black	1333-86-4	0.006	0.40		4041		
	plastics	epoxy resin	-	0.101	6.87		68698		
	inorganic material	silicondioxide	60676-86-0	0.485	33.14	40.41	331366	404106	
leadfinish	non noble metal	tin	7440-31-5	0.010	0.66	0.66	6600	6601	
plating	non noble metal	nickel	7440-02-0	0.001	0.05		468		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.05	1	470	
solder	non noble metal	tin	7440-31-5	0.000	0.00		35		
	noble metal	silver	7440-22-4	0.000	0.00		43		
	non noble metal	lead	7439-92-1	0.002	0.17	0.17	1656	1734	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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